

Claims

1. A flip-chip mounting electronic component, comprising:
plural terminals dotted on a mounting face; and
5 conductors formed on said terminals,
wherein said conductors are formed as remaining parts from growing
formation and/or removal, all the sums of heights of said terminals and said
conductors thereon are substantially equal, and tips of said conductors have a
substantially flat face.
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2. The flip-chip mounting electronic component according to claim 1,
wherein each of said conductors have a truncated cone or truncated
pyramid shape with a small tip.
- 15 3. An electronic component, comprising:
a circuit element and terminals formed on a ceramic plate face; and
conductors formed on said terminals,
wherein said conductors are formed as remaining parts from growing
formation and/or removal, all the sums of heights of said terminals and said
20 conductors thereon are substantially equal, and tips of said conductors have a
substantially flat face.
4. The electronic component according to claim 3,
wherein each of said conductors have a truncated cone or truncated
25 pyramid shape with a small tip.

5. The electronic component according to claim 3 or claim 4,
wherein said circuit element is a multiple or a network resistor or capacitor, or a network element composed of two or more elements selected from a capacitor, a resistor element and an inductor element.

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6. A method for producing a flip-chip mounting electronic component having plural terminals dotted on a mounting face and conductors formed on the terminals, comprising the steps of:

coating the mounting face with a conductor having a predetermined
10 thickness; masking corresponding positions for the terminal parts on the conductor surface; and removing the conductor except the mask parts, wherein these steps are performed in this order.

7. A circuit board, comprising:

15 plural flip-chip mounting lands dotted on a mounting face; and
conductors formed on said terminals,

wherein said conductors are formed as remaining parts from growing formation and/or removal, all the sums of heights of said lands and heights of said conductors thereon are substantially equal, and tips of said conductors
20 have a substantially flat face.

8. The circuit board according to claim 7,

wherein each of said conductors have a truncated cone or truncated pyramid shape with a small tip.

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9. A method for producing a circuit board having plural flip-chip

mounting lands dotted on a mounting face, comprising the steps of:

coating the mounting face with a conductor having a predetermined thickness; masking corresponding positions for the lands on the conductor surface; and removing the conductor except the mask parts, wherein these
5 steps are performed in this order.

10. A method for producing a package in which mounting face terminal parts of a flip-chip mounting electronic component and/or flip-chip mounting lands of a circuit board mounting face have conductors, the method
10 comprising:

forming the conductors as remaining parts from growing formation and/or removal; and securing the conductors of the circuit board and the electronic component or the conductors of the electronic component and the circuit board with solder or anisotropic conductive material.

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11. The method for producing a package according to claim 10,
wherein the conductors are constituted of copper and on surfaces thereof a nickel layer and a gold layer are formed in this order, and said securing is realized by fixing force of solder.